

AMENDMENTS TO THE CLAIMS

Please replace the claims, including all prior versions, with the listing of claims below.

Listing of Claims:

- 1-4. (Cancelled)
5. (Currently Amended) A method for grinding semiconductor wafers comprising:
grinding a surface of a semiconductor wafer with fixed abrasive grains and without free abrasive grains;
supplying free abrasive grains to said fixed abrasive grains; and
subsequently grinding said surface of a semiconductor wafer with said fixed abrasive grains and said free abrasive grains, wherein
said fixed abrasive grains have a larger diameter than said free abrasive grains.
6. (Cancelled)
7. (Currently Amended) The method of claim 5, wherein grinding includes at least one of both sides grinding of a semiconductor wafer [ø] and grinding of a chamfered portion.
8. (Cancelled)